

ERU chokes

ERU 25, helically wound

Series/Type: **B82559*A025**

Date: February 2016

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ERU chokes

B82559*A025

Helically wound

ERU 25

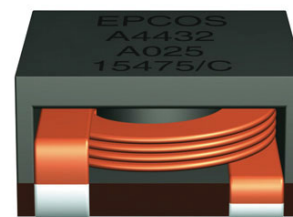
SMD

Rated inductance 0.44 20 μ H

Saturation current 15 ... 71 A

Construction

- High temperature ferrite core
- Magnetically shielded
- Helical winding
- Self-leaded construction
- Under body termination



Features

- High rated current
- Extremely low DC resistance
- Very low profile and extremely small footprint
- Suitable for pick-and-place processes
- RoHS-compatible
- Easily customized

Applications

Energy storage chokes for

- DC/DC converters
- VRM modules
- POL converters
- Solar converters

Terminals

Lead-free tinned

Marking

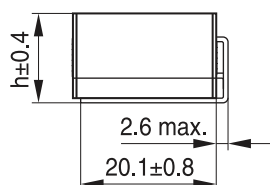
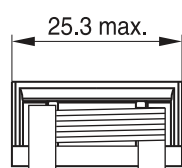
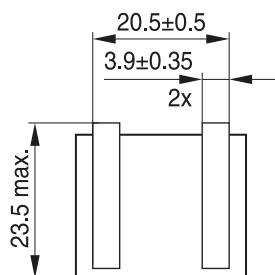
Manufacturer, ordering code, date of manufacture and production place (YYWWD/X),

Delivery mode and packing units

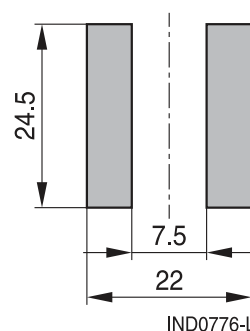
- Tray
- Blister tape on request

SMD

Dimensional drawing and layout recommendation



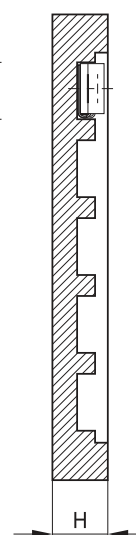
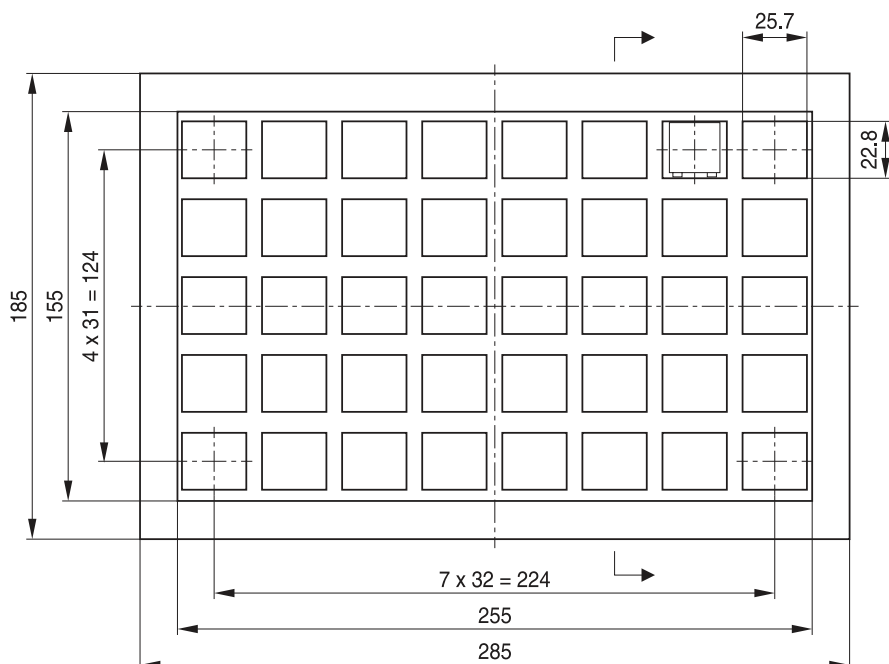
IND1280-P



IND0776-L

Dimensions in mm

Packing (tray)



Dimensions in mm

IND1216-V

Height (mm)		Packing unit	
component h	tray H	per tray	per box
9.6	19	40	280
11.1	21	40	280
12.8	23	40	240
14.6	23	40	240

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Technical data and measuring conditions

Rated inductance L_R	Measured at 10 kHz, 0.1 V, +25 °C
Inductance tolerance	±7%
Saturation current I_{Sat}	Current that will result in an approximately 10% drop in the inductance values at the specified temperature
DC resistance R_{DC}	Measured at +25 °C
Self-resonant frequency	> 2 MHz
High voltage: N1 - core	200 V DC, 1 s
Solderability (test of wettability of the pins)	(245 ±5) °C, (3 ±0.3) s, wetting of soldering area ≥95% (based on IEC 60068-2-58, solder bath method)
Resistance to soldering heat	To JEDEC J-STD 020D (Tc: +245 °C on pin)
Operating temperature	−40 °C ... +125 °C
Storage conditions (packaged)	−25 °C ... +40 °C, ≤ 75% RH

Characteristics and ordering codes

L_R	$I_{sat, 25°C}$	$I_{sat, 100°C}$	$R_{DC} (max)$	$R_{DC} (typ)$	Height h (nom.)	Approx. weight	Ordering code
μH	A	A	mΩ	mΩ	mm	g	
0.44	71	71	0.25	0.20	9.6	22.1	B82559A1042A025
1.25	50	48	0.45	0.40	11.1	24.4	B82559A2122A025
2.30	41	40	0.70	0.60	12.8	29.5	B82559A3232A025
2.90	33	29	1.15	1.00	9.6	21.8	B82559A3292A025
4.35	30	28	1.50	1.30	11.1	25.2	B82559A4432A025
6.10	28	24	1.85	1.60	11.1	26.3	B82559A5612A025
7.90	26	23	2.20	2.00	12.8	27.5	B82559A6792A025
10.00	24	22	2.55	2.20	12.8	29.6	B82559A7103A025
15.00	15	14	2.55	2.20	12.8	29.6	B82559A7153A025
20.00	15	14	3.25	2.80	14.6	33.0	B82559A9203A025

Sample kit available. Ordering code: B82559X002
For more information refer to chapter "Sample kits".

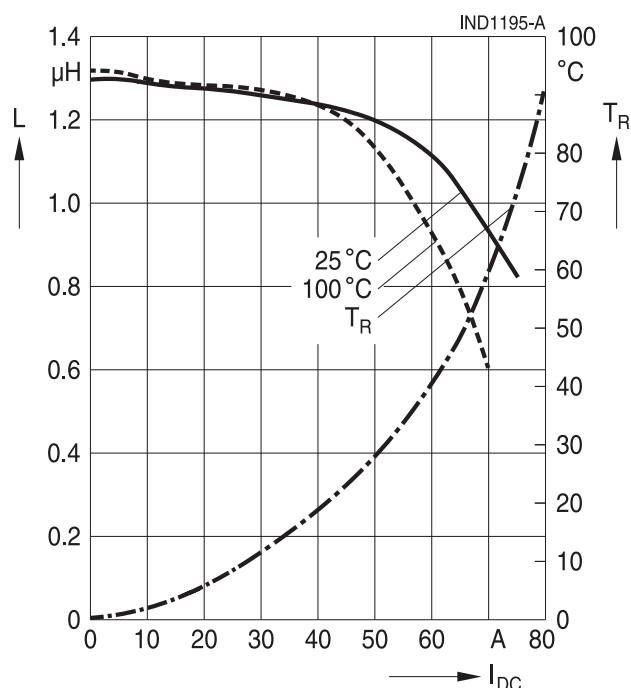
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Inductance L versus DC load current I_{DC}

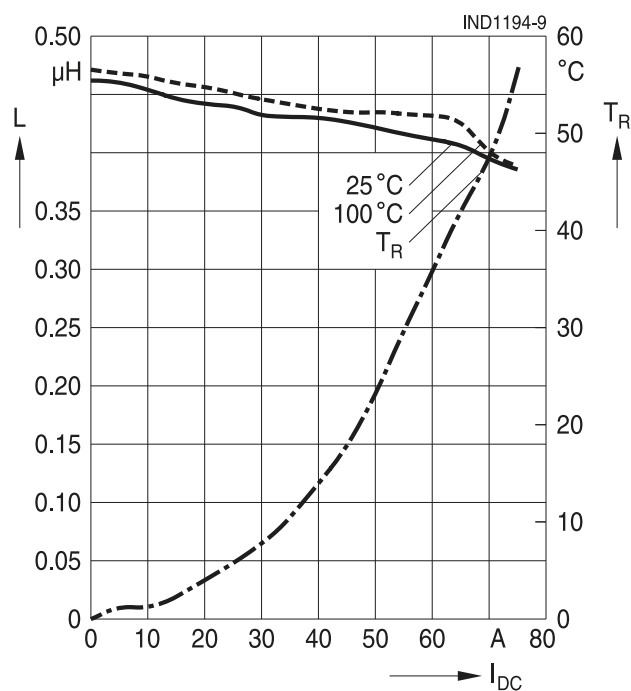
The temperature rise ΔT is measured at an ambient temperature of +25 °C. A current is applied for 30 minutes and the temperature is measured via a thermocouple placed on top of the device. No forced air cooling is applied.

The inductance vs current curves are generated by measuring the chokes at +25 °C and +100 °C.

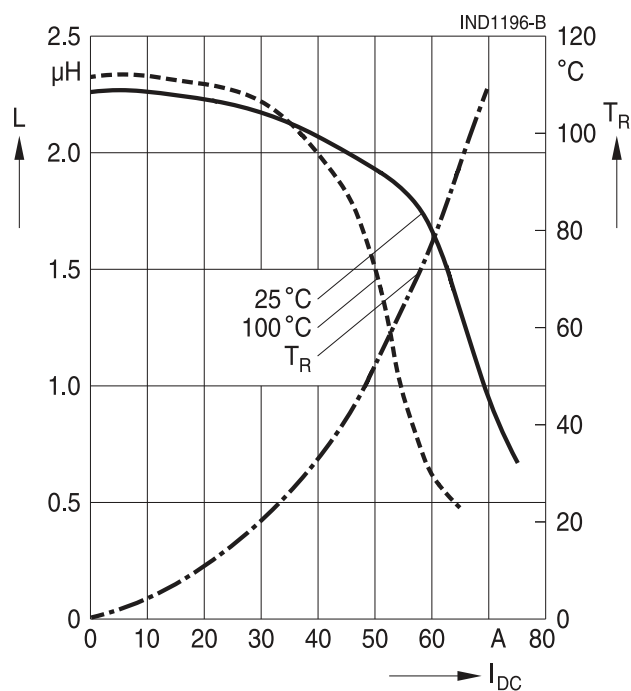
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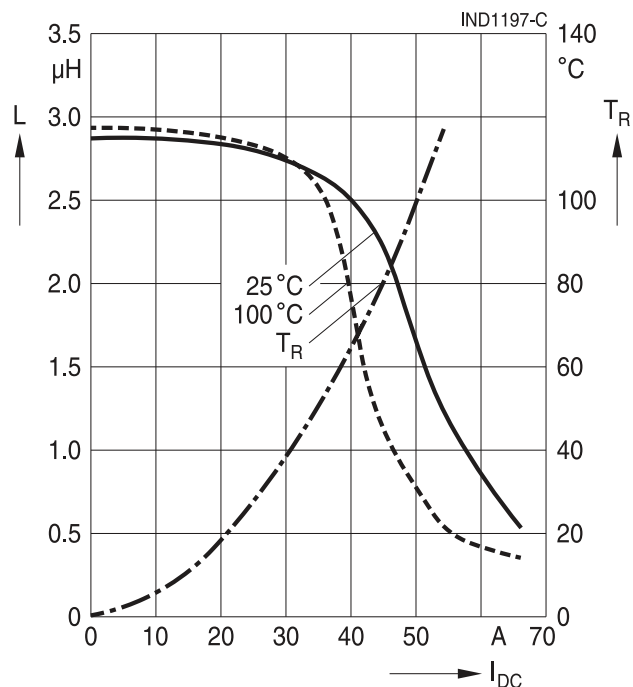


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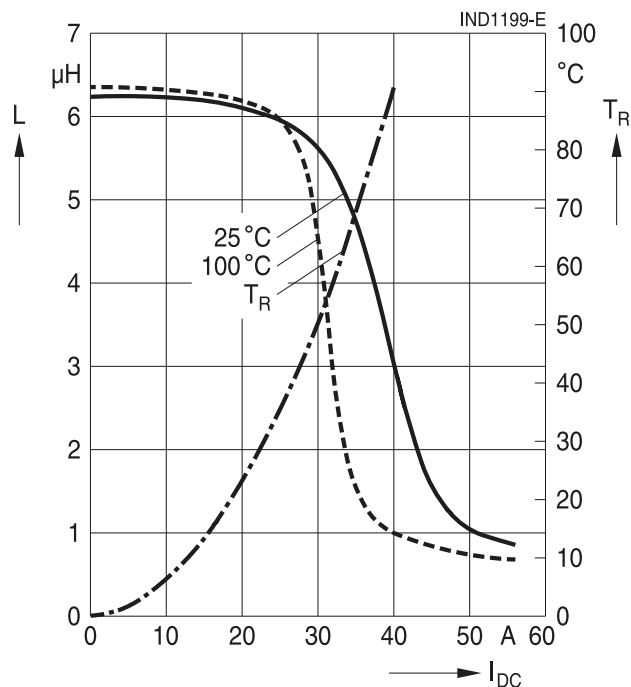


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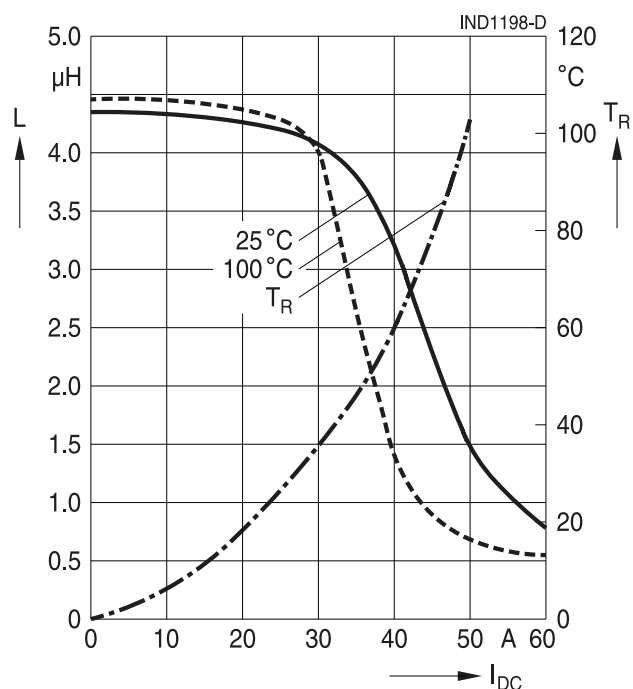
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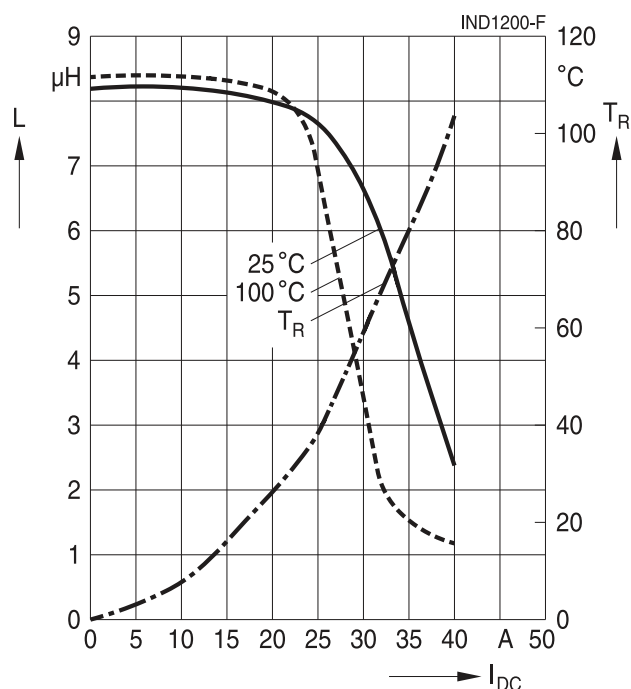
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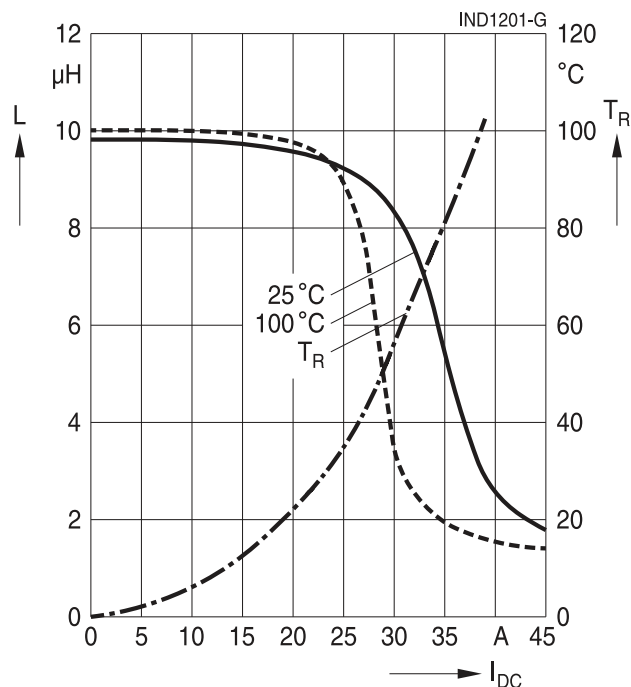


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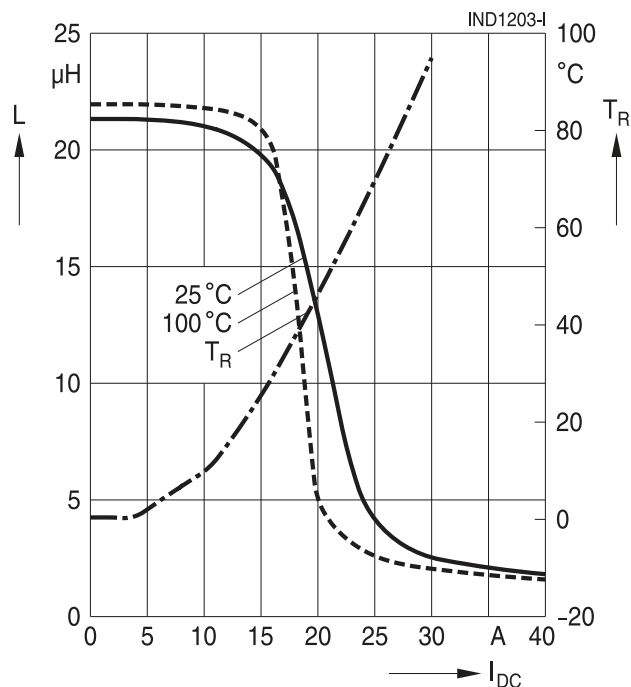


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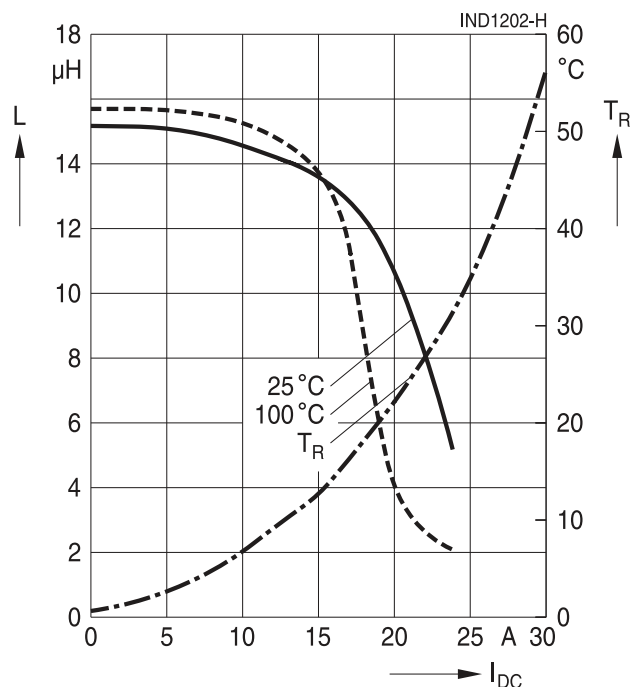
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Cautions and warnings

- Please note the recommendations in our Inductors data book (latest edition) and in the data sheets.
 - Particular attention should be paid to the derating curves given there.
 - The soldering conditions should also be observed. Temperatures quoted in relation to wave soldering refer to the pin, not the housing.
- If the components are to be washed varnished it is necessary to check whether the washing varnish agent that is used has a negative effect on the wire insulation, any plastics that are used, or on glued joints. In particular, it is possible for washing varnish agent residues to have a negative effect in the long-term on wire insulation.

Washing processes may damage the product due to the possible static or cyclic mechanical loads (e.g. ultrasonic cleaning). They may cause cracks to develop on the product and its parts, which might lead to reduced reliability or lifetime.
- The following points must be observed if the components are potted in customer applications:
 - Many potting materials shrink as they harden. They therefore exert a pressure on the plastic housing or core. This pressure can have a deleterious effect on electrical properties, and in extreme cases can damage the core or plastic housing mechanically.
 - It is necessary to check whether the potting material used attacks or destroys the wire insulation, plastics or glue.
 - The effect of the potting material can change the high-frequency behaviour of the components.
- Ferrites are sensitive to direct impact. This can cause the core material to flake, or lead to breakage of the core.
- Even for customer-specific products, conclusive validation of the component in the circuit can only be carried out by the customer.

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